

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2000-017444

(43)Date of publication of application : 18.01.2000

(51)Int.Cl.

C23C 18/22

C23C 18/31

(21)Application number : 10-183037

(71)Applicant : NEC KANSAI LTD

(22)Date of filing : 29.06.1998

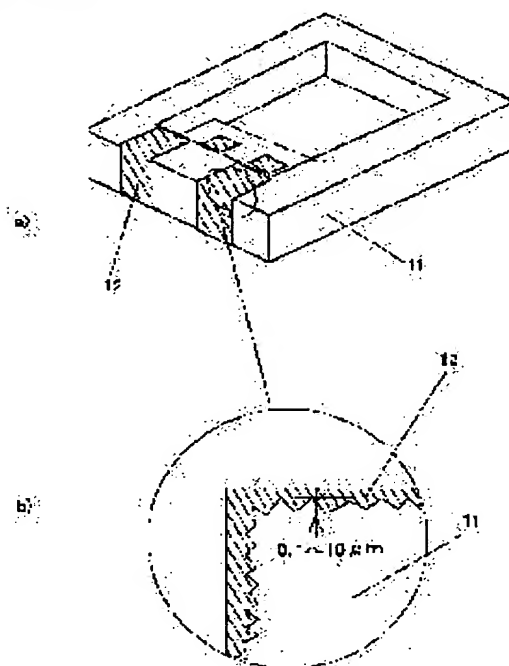
(72)Inventor : OURA KIKUO
FUJII KENZO

(54) RESIN MOLDING AND PRODUCTION OF RESIN MOLDING

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a resin molding capable of forming fine patterns and producing an inexpensive electron circuit structure and a process for producing this resin molding.

SOLUTION: The stage for directly laminating a metallic layer 12 on a resin 11 in the process for producing the resin molding directly laminated with the resin 11 consisting of a single material and the metallic layer 12 without the intervention of an adhesive layer consists of a stage for roughening the surface itself of the resin 11 to a surface roughness of ≥ 0.1 to ≤ 10 microns and a stage for footing the metallic layer 12 by direct electroless plating on the surface of the resin 11 roughened in this stage.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

Copyright (C); 1998,2003 Japan Patent Office